

(0,40mm) .01575"
SS4, ST4 SERIES

ULTRA FINE PITCH HEADER & SOCKET

SS4 Mates with:
 ST4
ST4 Mates with:
 SS4

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SS4 or www.samtec.com?ST4

Insulator Material:
 Black LCP
Contact Material:
 Phosphor Bronze
Plating:
 Au or Sn over 50µ" (1,27µm) Ni
Operating Temp Range:
 -55°C to +125°C
Current Rating:
 1.3A @ 80°C ambient
RoHS Compliant:
 Yes



Processing:
 Lead-Free Solderable:
 Yes
SMT Lead Coplanarity:
 (0,10mm) .004" max

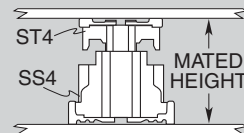
SS4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	K	TR
	-10, -20, -30, -40, -50	-3.00 = 3.00mm -3.50 = 3.50mm	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail		(Required in callout) -K = (3,51mm) .138" DIA Polyimide Film Pick & Place Pad	(Required in callout) -TR = Tape & Reel

LEAD STYLE	A	B
-3.00	(2,85) .112	(3,50) .138
-3.50	(3,35) .132	(4,00) .157

4mm Stack Height	Rated @ 3dB Insertion Loss
Single-Ended Signaling	7.0 GHz / 14 Gbps
Differential Pair Signaling	4.5 GHz / 9 Gbps

Complete test data available at www.samtec.com?SS4, www.samtec.com?ST4 or contact sig@samtec.com

MATED HEIGHT



MATED HEIGHT*		
ST4 LEAD STYLE	SS4 LEAD STYLE	
	-3.00	-3.50
-1.00	(4,00) .157	(4,50) .177
-1.50	(4,50) .177	(5,00) .197
-2.50	(5,50) .217	(6,00) .236

*Processing conditions will affect mated height.

ST4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	P	TR
	-10, -20, -30, -40, -50	-1.00 = 1.00mm -1.50 = 1.50mm -2.50 = 2.50mm	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail		(Required in callout) -P = Pick & Place Pad	(Required in callout) -TR = Tape & Reel

LEAD STYLE	A	B
-1.00	(1,00) .039	(3,08) .121
-1.50	(1,50) .059	(3,58) .141
-2.50	(2,50) .098	(4,58) .180

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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